

现场活动手册

ONSITE EVENT HANDBOOK

2019 年 4 月 24-26 日

APRIL 24-26, 2019

上海世博展览馆

SHANGHAI WORLD EXPO EXHIBITION &
CONVENTION CENTER



主办单位 ORGANISED BY:



同期举办 HELD IN CONJUNCTION:



智能工厂展示区

Smart Factory Display Zone

展示区一 | Display Zone 1

智能制造梦工厂—生产线

Smart Manufacturing Dream Factory Demo Line

演示时间 | Demo Time: 10:00/11:00/13:30/14:30/15:30

演示地点 | Demo Location: 2S90



参与活动有机会获得
个人签名移动电源一个
Chance to get a power bank with customized signature



展示区二 | Display Zone 2

NEW “中国智造” SMT 生产线展示区

China Smart Manufacturing SMT Demo Line Display Zone

演示地点 | Demo Location: 2R50



Onsite Events

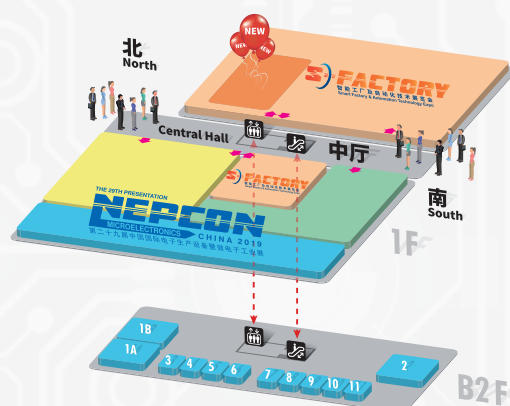
现场活动一览



4.24.2019 星期三 Wednesday	*SMTA华东高科技技术研讨会 *SMTA China East Technology Conference		SMTA华东高科技设备研讨会 SMTA China East Vendor Conference
	10:30-15:30 B2层, 6号会议室 / Meeting Room No.6, Floor B2		10:30-15:25 1号馆, 1N22 / 1N22, Hall 1
	*SMTA华东高科技会议-INEMI低温焊接技术研讨会 (全英文演讲) *SMTA China East Conference - iNEMI Low Temperature Soldering Workshop (Speech in English)		中国国际电子制造峰会 China International Electronics Manufacturing Summit
	09:45-17:15 B2层, 9号会议室 / Meeting Room No.9, Floor B2		09:30-12:00 B2层, 1号会议室 / Meeting Room No.1, Floor B2
	中国国际电子制造峰会 分论坛1: 5G驱动智能制造论坛 China International Electronics Manufacturing Summit Track 1: 5G-Driven Smart Manufacturing Forum	第二届中国数字化制造高峰论坛 The 2nd China Digital Manufacturing Summit	质胜之道—5G时代下的消费电子质量标准论坛 All Quality Matters – Consumer Electronics Quality Standard Forum in 5G Era
	13:30-15:45 B2层, 1号会议室 / Meeting Room No.1, Floor B2	10:00-16:00 智慧剧院 / Smart Theatre	13:30-17:00 B2层, 5号会议室 / Meeting Room No.5, Floor B2
4.25.2019 星期四 Thursday	第十三届“NEPCON与智慧工厂1.0— 电子制造的未来”主题研讨会 The 13th Themed Symposium of NEPCON and Smart Factory 1.0 - Future of Electronics Manufacturing	“智能可穿戴产品中印刷电子与微组装技 术”创新论坛 Innovation Forum on "Printed Electronics & Micro-Assembly Technology in Smart Wearable Products"	日本电子午间研讨会 JEOL Lunch Seminar
	13:30-15:30 2R40	13:30-16:30 B2层, 7号会议室 / Meeting Room No.7, Floor B2	12:00-13:00 B2层, 11号会议室 / Meeting Room No.11, Floor B2
	*SMTA华东高科技技术研讨会 *SMTA China East Technology Conference	SMTA华东高科技设备研讨会 SMTA China East Vendor Conference	2019 (第二十四届) 上海国际SMT技术高级研 讨会 2019 (The 24th) Shanghai Int'l SMT High - level Conference
	10:30-14:55 B2层, 6号会议室 / Meeting Room No.6, Floor B2	10:30-15:25 1号馆, 1N22 / 1N22, Hall 1	09:50-16:20 B2层, 5号会议室 / Meeting Room No.5, Floor B2
	中国国际电子制造峰会 分论坛2: 先进封装技术论坛 China International Electronics Manufacturing Summit Track 2: Advanced Packaging Technology Forum	第二届中国数字化制造高峰论坛 The 2nd China Digital Manufacturing Summit	2019 AUTOMOTIVE WORLD CHINA新能源汽车三 电系统开发与测试技术大会 2019 AUTOMOTIVE WORLD CHINA Conference on Development and Testing Technologies for NEV Electromobility System
	09:55-15:55 B2层, 1号会议室 / Meeting Room No.1, Floor B2	09:50-16:00 智慧剧院 / Smart Theatre	10:00-16:30 B2层, 2号会议室 / Meeting Room No.2, Floor B2
4.26.2019 星期五 Friday	“中国电子工业静电防护2019”专业 论坛 2019 Forum on Electrostatic Protection in China's Electronics Manufacturing Industry	第十三届“NEPCON与智慧工厂1.0— 电子制造的未来”主题研讨会 The 13th Themed Symposium of NEPCON and Smart Factory 1.0 - Future of Electronics Manufacturing	日本电子午间研讨会 JEOL Lunch Seminar
	13:30-16:30 B2层, 7号会议室 / Meeting Room No.7, Floor B2	10:15-15:30 2R40	12:00-13:00 B2层, 11号会议室 / Meeting Room No.11, Floor B2
	2019 AUTOMOTIVE WORLD CHINA新能源汽车三电系统开发与测试技术大会 2019 AUTOMOTIVE WORLD CHINA Conference on Development and Testing Technologies for NEV Electromobility System		NEPCON工程师沙龙暨SMT之家会员见面会 NEPCON Engineers' Salon and SMT Home Member Gathering
	10:00-16:30 B2层, 2号会议室 / Meeting Room No.2, Floor B2		13:00-15:45 智慧剧院 / Smart Theatre

* 打星号的为收费会议
* The meetings marked with "*" shall be charged.

具体会议日程请以会议现场演讲为准, 解释权归主办单位所有。
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- 表面贴装展区
Surface Mount Technology Pavilion
- 测试测量展区
Test & Measurement Pavilion
- 智慧工厂展区
Smart Factory & Automation Technology Expo
- 电子微组装及Sip工艺展示区
Electronic Micro-assembly & SiP Process Pavilion
- 焊接及点胶喷涂展区
Soldering & Dispensing Pavilion

* 欲前往1—11号会议室请至展馆B2层 / Meeting Rooms No.1-11 are on Floor B2 of the Venue

SMTA华东高科技会议 SMTA China East Conference

>> 高科技技术研讨会

>> Technology Conference (CE19-TC1)

时间: 2019年4月24日10:30-15:30 (星期三)

Time: 10:30-15:30, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆B2层6号会议室

Location: Meeting Room No.6, B2, Shanghai World Expo Exhibition & Convention Center

主办单位:
ORGANISED BY:



支持单位:
SUPPORTED BY:



会议主席: 董林, 中国SMTA技术顾问委员会委员, 优而备智自动化设备(上海)有限公司客户支援经理
Conference Chairman: Lin Dong, Member of SMTA China Technical Advisory Committee, Customer Support Manager of Europlacer (Shanghai) Co., Ltd.

时间/Time	议题/Topic	主讲人/Speaker
10:30 - 11:05	智能工厂 (Industrie4.0) 系统原理概述以及对电子制造业的影响 Management Overview of The Smart Factory (Industrie 4.0) Principles and affects In Electronics Manufacturing (CE19-TC1.1)	萨奇鲁文, Mentor, A Siemens Business Sagi Reuven, A Siemens Business, Mentor
11:05 - 11:40	新型Sn-Bi-Ag低温焊锡在电子组装的应用 New Generation Sn-Bi-Ag Low Temp Solder for SMT Assembly (CE19-TC1.2)	林国书博士, 升贸科技股份有限公司 Dr. Kuo-Shu Lin, Shengmao Technology Inc.
11:40 - 12:15	ACF&ACP细间距制程研发及制造挑战 ACF and ACP Fine Pitch Assembly and Manufacturing Challenges (CE19-TC1.3)	潘俊杰, 纬创资通(昆山)有限公司 Tim C.C. Pan, Wistron InfoComm (Kunshan) Co., Ltd.
12:15 - 13:45	午餐 Lunch Break	
13:45 - 14:20	钢网质量和工艺对焊膏印刷的影响 Impact of Stencil Quality & Technology On Solder Paste Printing Performance (CE19-TC1.4)	殷雪冬, 镓泰科技(苏州)有限公司 Evan Yin, Indium Corporation (Suzhou) Co., Ltd.
14:20 - 14:55	高可靠性无铅焊料的研究进展 An Update On High Reliability Lead-Free Solder Alloys (CE19-TC1.5)	朱军桦, AIM Solder Dillon Zhu, AIM Solder
14:55 - 15:30	pH中性清洗剂—市场的预期和现场实验表现 pH Neutral Cleaning Agents - Market Expectation & Field Performance (CE19-TC1.6)	纪建光, ZESTRON北亚分公司 Jerry Ji, ZESTRON Asia North

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Conference Program

研讨会会议程



SMTA华东高科技会议

SMTA China East Conference

>> 高科技技术研讨会

>> Technology Conference (CE19-TC2)

时间: 2019年4月25日10:30-14:55 (星期四)

Time: 10:30-14:55, April 25th, 2019 (Thursday)

地点: 上海世博展览馆B2层6号会议室

Location: Meeting Room No.6, B2, Shanghai World Expo Exhibition & Convention Center

主办单位:
ORGANISED BY:



支持单位:
SUPPORTED BY:



会议主席: 周辉, 中国SMTA技术顾问委员会委员, 东莞新能德科技有限公司工程部总监
Conference Chairman: Henley Zhou, Member of SMTA China Technical Advisory Committee, PME / Engineering Director of Dongguan NVT Technology Co., Ltd.

时间/Time	议题/Topic	主讲人/Speaker
10:30 - 11:05	新型无卤聚对二甲苯, 有助于增强柔性、刚性及高密度电子元件在水中和其他腐蚀环境中的耐用性能 A New Halogen-Free Parylene for Robust Performance of Flexible, Rigid and High-Density Electronics In Water and Other Corrosive Environments (CE19-TC2.1)	瑞克西 库马博士, 特殊涂敷系统公司 Dr. Rakesh Kumar, Specialty Coating Systems, Inc.
11:05 - 11:40	满足高性能要求应用的无铅合金 High Reliability Lead-Free Alloys for Performance-Critical Applications (CE19-TC2.2)	余瑜, 麦德美爱法电子部 William Yu, MacDermid Alpha Electronics Solutions
11:40 - 12:15	细密间距元件的印刷工艺设计 Printing Process Design for High Density Low Space Component (CE19-TC2.3)	瞿艳红, 镭泰科技(苏州)有限公司 Wisdom Qu, Indium Corporation (Suzhou) Co., Ltd.
12:15 - 13:45	午餐 Lunch Break	
13:45 - 14:20	应用于倒装芯片和SIP封装的回流后黏度降低的新型助焊剂 Novel Fluxes With Decreased Viscosity After Reflow for Flip Chip and SiP Assembly (CE19-TC2.4)	陈芬, 镭泰科技(苏州)有限公司 Fiona Chen, Indium Corporation (Suzhou) Co., Ltd.
14:20 - 14:55	pH 值对清洗剂特性和性能的影响 The Effect of pH: Cleaning Agent Properties and Performance in Production (CE19-TC2.5)	高伟, 上海凯晟清洁材料有限公司 Daniel Gao, Shanghai KYZEN Cleaning Materials Co., Ltd.

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SMTA华东高科技会议 SMTA China East Conference

>> 高科技设备研讨会

>> Vendor Conference (CE19-VC1)

时间: 2019年4月24日10:30-15:25 (星期三)

Time: 10:30-15:25, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆1号馆1N22展位

Location: Booth 1N22, Hall 1., Shanghai World Expo Exhibition & Convention Center

主办单位:
ORGANISED BY:



支持单位:
SUPPORTED BY:



会议主席: 张泓, 上海鉴龙电子工程有限公司技术总监

Conference Chairman: Hong Zhang, Technical Director of Shanghai J & L Electronic Engineering Co., Ltd.

时间/Time	议题/Topic	主讲人/Speaker
10:30 - 10:55	人工智能AI在智能物流中的应用 Applications of Artificial Intelligence In SMT Logistics Management (CE19-VC1.1)	沈懿俊, 上海挚锦科技有限公司 Billy Shen, Neotel Technology Co., Ltd.
11:00 - 11:25	实现工厂静电监控可视化智能管理 Smart and Visualization Management of ESD Control In SMT Factory (CE19-VC1.2)	唐仕晨, 上海鉴龙电子工程有限公司 Tobin Tang, Shanghai J & L Electronic Engineering Co., Ltd.
11:30 - 11:55	让eMMC烧录不再烧脑 Mastering eMMC Device Programming (CE19-VC1.3)	张军强, 美国BPM公司 Dragon Zhang, BPM Microsystems
12:00 - 12:25	多功能3D检测与测量 Multi Function 3D Measurement (CE19-VC1.4)	李元, 香港凯能自动化设备有限公司 Yuan Li, Kasion Automation Limited
12:30 - 13:30	午餐 Lunch Break	
13:30 - 13:55	返修的应用 Rework Application (CE19-VC1.5)	周铭, 美国VJE公司 Jeremy Zhou, VJ Electronix Inc.
14:00 - 14:25	导热胶点胶方案 Thermal Interface Material Dispensing Solution (CE19-VC1.6)	徐东华, 美国PVA公司 Scott Xu, PVA Inc.
14:30 - 14:55	针对于多拼板的ICT和芯片烧录的一体式解决方案 ICT+MultiWriter for Multi-Panel (CE19-VC1.7)	张勇荣, 美国查胜公司 Bruce Zhang, Checksum
15:00 - 15:25	机械手上下料应用趋势 (3C产品) Trend of SCARA Robot Assembly Application (3C Product) (CE19-VC1.8)	于军, 东莞市安达自动化设备有限公司 Jun Yu, Dongguan Anda Automation Equipment Co., Ltd.

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Conference Program

研讨会会议程



SMTA华东高科技会议

SMTA China East Conference

>> 高科技设备研讨会

>> Vendor Conference (CE19-VC2)

时间: 2019年4月25日10:30-15:25 (星期四)

Time: 10:30-15:25, April 25th, 2019 (Thursday)

地点: 上海世博展览馆1号馆1N22展位

Location: Booth 1N22, Hall 1., Shanghai World Expo Exhibition & Convention Center

主办单位:
ORGANISED BY:



支持单位:
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会议主席: 张泓, 上海鉴龙电子工程有限公司技术总监
Conference Chairman: Hong Zhang, Technical Director of Shanghai J & L Electronic Engineering Co., Ltd.

时间/Time	议题/Topic	主讲人/Speaker
10:30 - 10:55	最新的自动化元件数料趋势-X射线点料技术及生产管理信息共享 The Latest Component Counting Trend - X-Ray Component Counting and Data Sharing With MES (CE19-VC2.1)	周铭, 美国VJE公司 Jeremy Zhou, VJ Electronix Inc.
11:00 - 11:25	BGA结构混装焊点的可靠性研究 Reliability Research of BGA Structure Mixed Assembled Joints (CE19-VC2.2)	黄家强, 深圳市同方电子新材料有限公司 Jiaqiang Huang, Shenzhen City TongFang Electronic New-material Co., Ltd.
11:30 - 11:55	三防涂敷工艺优化及趋势 Optimizing Conformal Coating Configurations & Market Trends (CE19-VC2.3)	孟祥翔, 美国PVA公司 Simon Meng, PVA Inc.
12:00 - 12:25	基于全程精确追溯的大数据及生产管理 (MES) 系统 Big Data Technology and MES System Based On Full Traceability (CE19-VC2.4)	曹东云, 宁波中电集创科技有限公司 Dongyun Cao, Ningbo CECIC Technology Co., Ltd.
12:30 - 13:30	午餐 Lunch Break	
13:30 - 13:55	针对于多拼板的ICT和芯片烧录的一体式解决方案 ICT + MultiWriter for Multi-Panel (CE19-VC2.5)	张勇荣, 美国查胜公司 Bruce Zhang, Checksum
14:00 - 14:25	Pillarhouse选择性波峰焊介绍 Introduction of Pillarhouse Selective Wave Soldering (CE19-VC2.6)	姜霖, 英国Pillarhouse公司 Allan Jiang, Pillarhouse Int'l
14:30 - 14:55	让eMMC烧录不再烧脑 Mastering eMMC Device Programming (CE19-VC2.7)	张军强, 美国BPM公司 Dragon Zhang, BPM Microsystems
15:00 - 15:25	涂敷过程中的常见缺陷检测与预防 Common Defects Inspection and Prevention In Conformal Coating Process (CE19-VC2.8)	杨晓龙, 东莞市安达自动化设备有限公司 Xiaolong Yang, Dongguan Anda Automation Equipment Co., Ltd.

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Conference Program 研讨会日程

SMTA华东高科技会议-iNEMI低温焊接技术工作坊

SMTA China East Conference - iNEMI Low Temperature Soldering Workshop

时间: 2019年4月24日 09:45-17:15 (星期三)

Time: 09:45-17:15, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆B2层, 9号会议室

Location: Meeting Room 9, B2/F, Shanghai World Expo Exhibition & Convention Center

时间/Time	议题/Topic	主讲人/Speaker
09:30 - 09:45	签到 Sign for Workshop Attendance	
09:45 - 10:00	欢迎及研讨会简介 Welcome and Workshop Overview	傅浩博士, iNEMI国际电子生产商联盟 Dr. Haley Fu, Director for Asia Pacific & Project Management, iNEMI
10:00 - 10:30	使用低温焊接的表面贴装技术 Surface Mount Technology Using Low Temperature Soldering	陈国冠, Intel英特尔, CPTD技术项目经理 Kok Kwan Tang, CPTD Technical Program Manager, Intel
10:30 - 10:55	电子封装中的低温焊接合金系统 Low Temperature Solder Alloy System in Electronic Packaging	沈骏教授, 重庆大学, 博导 Dr. Jun Shen, Professor, PhD Advisor, Chongqing University
10:55 - 11:20	iNEMI基于锡铋的低温焊接工艺和可靠性项目报告 iNEMI BiSn-Based Low-Temperature Soldering Process and Reliability Project Report	傅浩博士, iNEMI国际电子生产商联盟, 亚太区及项目管理总监 Dr. Haley Fu, Director for Asia Pacific & Project Management, iNEMI
11:20 - 11:45	低温焊接总览 Low Temperature Solder Overview	张惠勇, Dell戴尔, 全球供应商质量经理 Jacky Zhang, Global Supplier Quality Manager, Dell
11:45 - 13:00	午餐 Lunch Break	
13:00 - 13:25	新一代SMT低温焊接材料的开发 Development of Low Temperature Solder for Next Generation SMT	Naoki Kubota, 田村电子, 技术销售专员 Naoki Kubota, Technical Sales Specialist, Tamura
13:25 - 13:50	用于SMT的低温焊接 Low Temperature Solder for SMT	张先锋, 伟创力, 运营工程经理 Domini Zhang, Operations Engineering Manager, Flex
13:50 - 14:05	茶歇Tea break	
14:05 - 14:30	先进的表面贴装无铅低温焊接材料 Advanced Low Temp Lead-free Solder for SMT Assembly	曾华承, 昇贸科技, 研发副总裁, 美国总经理 Watson Tseng, Vice President of R&D and General Manager of America, Shengmao Technology
14:30 - 14:55	用于下一代装配的高可靠低温焊接合金 High Reliability Low Temperature Soldering Alloys for Next Generation Assemblies	杨莉, 麦德美爱法, 中国区市场经理 Annie Yang, Regional Marketing Manager - China, MacDermid Alpha

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Conference Program

研讨会议程



14:55 - 15:20	电子装配中的低温焊接技术 — 对装配和可靠性的挑战 Application of Low Temperature Soldering Technology in Electronic Assembly - Assembly and Reliability Challenges	尚攀举博士, 华为, 资深工程师 Dr. Panju Shang, Senior Engineer, Huawei
15:20 - 15:30	茶歇 Tea break	
15:30 - 15:55	优诺LTS解决方案和应用实践—NWO的解决与LTS混合焊点评价新方法 Solution and Application Practice of Eunow's LTS paste - NWO Solution and new method of LTS Mixed Solder Joint Evaluation	陈钦, 苏州优诺, 研发经理 Qin Chen, R & D Manager, Eunow
15:55 - 16:20	低温无铅焊料高速失效特征及应用实例 High Speed Shear Results of Low Temperature Solder	王鑫博士, Quanta广达, SMT实验室协理 Dr. Xin Wang, SMT Lab Associate Manager, Quanta
16:20 - 17:00	座谈问答 Panel discussion	
17:00 - 17:15	总结 Wrap up	



中国国际电子制造峰会

China International Electronics Manufacturing Summit

时间: 2019年4月24日 09:30-12:00 (星期三)

Time: 09:30-12:00, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆B2层, 1号会议室

Location: Meeting Room 1, B2/F, Shanghai World Expo Exhibition & Convention Center

主持人: 工业和信息化部国际经济技术合作中心 姜冠雄副主任

Moderator: JIANG Guanxiong, Deputy Director General, Center for International Economic and Technological Cooperation, Ministry of Industry and Information Technology (CIETC-MIT)

时间/Time	议题/Topic	主讲人/Speaker
09:30 - 09:40	工业和信息化部原党组成员金书波致辞 Remarks by JIN Shubo, Former Party Member of the Ministry of Industry and Information Technology	
09:40 - 09:50	工业和信息化部电子信息司副司长吴胜武致辞 Remarks by WU Shengwu, Deputy Director General, Department of Electronics and Information Service of the Ministry of Industry and Information Technology	
09:50 - 10:00	励展博览集团致辞 Speech by Reed Exhibitions	
10:00 - 10:15	产融结合, 联盟创新 Industry and Financial Collaborative Development Promotes Innovation	朱立锋, 中国电子信息产业集团公司, 总经理助理 Lifeng ZHU, General Manager Assistant, China Electronics Corporation
10:15 - 10:30	5G+工业互联网 5G and Industry of Internet	陈山枝博士, 中国信息通信科技集团有限公司副总裁, 无线移动通信国家重点实验室主任 Dr. Shanzhi CHEN, EVP of China Information Communications Technologies Group Corporation, and the director of State Key Laboratory of Wireless Mobile Communications
10:30 - 10:45	产融结合推动电子制造业高质量发展 Industry-Finance Integration Promotes High Quality Development of the Electronics Manufacturing Industry	张春生, 国家集成电路产业投资基金, 副总经理 Chunsheng ZHANG, Deputy General Manager, National Integrated Circuit Industry Investment Fund
10:45 - 11:00	智能化浪潮下通信运营商的发展机遇与挑战 The Challenges and Opportunities for Communication Operators in the Tide of Intelligent Manufacturing	周骏, 中国电信集团制造业信息化应用基地, 执行副总经理, 首席咨询专家 Jun ZHOU, Executive Vice General Manager and Chief Consultant Expert China Telecom Manufacturing Industry Information Technology Application Base
11:00 - 11:15	互联世界中的智能制造 Intelligent Manufacturing in an Interconnected World	孙伟, ABB (中国) 机器人组装与测试应用中心负责人 Wei SUN, Head of Center for Robot Assembly and Test Application, ABB (China)
11:15 - 11:30	松下智能工厂解决方案 Panasonic Smart Factory Solution	沈崎, 松下电器机电(中国)有限公司 PA 事业部, 部长 Qi Shen, General manager, Panasonic Industrial Devices Sales (China) Co., Ltd Process Automation Business Unit
11:30 - 12:00	领导巡馆 Exhibition Touring	

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中国国际电子制造峰会

分论坛一：5G驱动智能制造论坛

China International Electronics Manufacturing Summit

Track 1: 5G-Driven Smart Manufacturing Forum

时间: 2019年4月24日 13:30-15:45 (星期三)
Time: 13:30-15:45, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆B2层, 1号会议室
Location: Meeting Room 1, B2/F, Shanghai World Expo Exhibition & Convention Center

时间/Time	议题/Topic	主讲人/Speaker
13:30 - 14:55	5G对电子制造带来的挑战和机遇 Challenges and Opportunities Brought by 5G for Electronics Manufacturing	刘哲, 中兴通讯股份有限公司, 总工程师 Zhe Liu, Chief Engineer, ZTE
14:55 - 15:20	5G将打造工业4.0高阶版 5G Will Accelerate Industry 4.0 to Advanced Pro	睦宾, Keysight, 资深工程师 Bin Gui, Sr. Application Engineer, Keysight
15:20 - 15:45	《智能制造的认知和实践》 Cognition and Practice of Intelligent Manufacturing	刘刚, 江苏省电子学会组装自动化委员会秘书长 Liu Gang, Secretary General of the Assembly Automation Committee, Jiangsu Institute of Electronics



中国国际电子制造峰会

分论坛二：先进封装技术论坛

China International Electronics Manufacturing Summit

Track 2: Advanced Packaging Technology Forum

时间: 2019年4月25日 09:30-15:55 (星期四)

Time: 09:30-15:55, April 25th, 2019 (Thursday)

地点: 上海世博展览馆B2层, 1号会议室

Location: Meeting Room 1, B2/F, Shanghai World Expo Exhibition & Convention Center

主持人: Yole Developpement

Host: Yole Developpement

时间/Time	议题/Topic	主讲人/Speaker
09:55 - 10:00	主办方致辞 Speech by Organizer	
10:00 - 10:30	手机射频模组系统级封装 (SiP) 的市场和技术趋势 Market and Technology Trends for RF SiP for Mobile	Santosh Kumar, Yole韩国, 首席技术分析师 Santosh Kumar, Principal Analyst, Yole Korea
10:30 - 11:00	华进先进封装技术介绍 Advanced Packaging in NCAP	王启东, 华进半导体封装先导技术研发中心有限公司, 研发部高级经理 Dr. Qidong Wang, Senior Manager R&D department, NCAP
11:00 - 11:30	ASM SiP量产 SMT 解决方案 ASM SMT Solution in High Volume SiP Production	徐骥, 先进装配系统有限公司, 产品市场经理 Ji Xu, Product Marketing Manager, ASM Assembly Systems Ltd.
11:30 - 12:00	针对高性能SiP集成工艺的基板设计策略 Substrate Strategy for the High Performance SiP Integration	Farhang Yazdani, BroadPak Corporation, 总裁兼首席执行官 Farhang Yazdani, the President and CEO of BroadPak Corporation
12:00 - 13:30	午餐及参观展览 Lunch and Exhibition Touring	
13:30 - 14:00	晶圆级封装以及异质结构集成 Wafer Level Packaging and Heterogeneous Integration	刘宏钧, 苏州晶方半导体科技股份有限公司, 市场部副总 Russell Liu, VP of Marketing Department, China Wafer Level CSP Co., Ltd.
14:00 - 14:30	垂直精密板级封装 (PLP) 高速电镀和湿制先进工艺 Advances in High Speed Plating and Wet Processing for Vertical Glass Fine-Line PLP	Raoul Schroeder, Semsysco
14:30 - 15:00	半导体微小化集成倡议—SiP制程工艺简介 Miniaturization initiatives-SiP technology briefing	卢建宏, 环鸿科技股份有限公司, 移动无线连接方案事业处资深处长 David Lu, Senior Director Mobile Wireless Connectivity BU, Universal Global Scientific Industrial Co., Ltd.
15:00 - 15:30	SiP测试解决方案 SiP Testing Solutions	UTAC (TBC)
15:30 - 15:55	圆桌讨论 Round table discussion	

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Conference Program

研讨会议程



第二届中国数字化制造高峰论坛

The 2nd China Digital Manufacturing Summit

时间: 2019年4月24日 10:00-16:00 (星期三)
Time: 10:00-16:00, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆, 智慧剧院
Location: Smart Theatre, Shanghai World Expo Exhibition & Convention Center

时间/Time	议题/Topic	主讲人/Speaker
09:30 - 10:00	签到 Sign-in	
10:00-10:10	主办方致辞 Speech by Organizer	
10:10 - 10:30	数字万物—数字化未来 Digital Everything - The Digital Future	黄鹤鸣, 中德人工智能研究, 副院长 Heming Huang, Vice-president, China-Germany Artificial Intelligence Institute (CGAII)
10:30 - 11:00	5阶魔方透视, 拥抱新兴智造—赛意助力新智造转型落地 Embracing the Emerging Intelligent Manufacturing -SIE's Helps the Transformation and Execution of New Intelligent Manufacturing Projects	温明振, 广州赛意信息科技股份有限公司, 赛意首席规划师 Mingzhen Wen, Chief Planner, Guangzhou SIE Consulting Co., Ltd.
11:00 - 11:30	美云智数数字化打造透明工厂 Meicloud's Digital Construction of a Transparent Factory	陈昕乐, 深圳美云智数科技有限公司, 供应链云事业部总经理 Xinle Chen, General Manager of Supply Chain Cloud Division, Shenzhen Meicloud Technology Co., Ltd.
11:30 - 12:00	《SICK 推动您的“工业4.0/智能制造”大步向前》 《SICK Driving Your Industry 4ward》	崔丽丽, 广州市西克传感器有限公司, 市场总监 Lili Cui, Marketing Director, Guangzhou SICK Sensor Co., Ltd.
12:00 - 13:30	午间休息 Lunch Break	
13:30 - 14:00	数字化智能配电助力工业升级 Digital Smart Power for Industrial Upgrading	王少辉, ABB(中国)有限公司, 全国技术销售总监 Shaohui Wang, Technology Sales Manager, ABB
14:00 - 14:30	AMPOS伙伴圈—如何利用科技和大数据实现持续绩效管理 AMPOS Partnership Circle - How to Use Technology and Big Data to Achieve Sustainable Performance Management	吴西恩 博士, 上海掘捷信息科技有限公司, 全球销售主管 Sean H. Wu ph.D, Head of sales, Global, Ampostech
14:30 - 15:00	智能网通—从现状到未来 Smart Connectivity: Now and into the Future	马锋, 摩莎科技(上海)有限公司, 中国区智能制造行业总监 Feng Ma, Director, China Smart Manufacturing Industry, Moxa Technologies (Shanghai) Co., Ltd.
15:00 - 15:30	PISX DT解决方案助力制造行业数字化转型 PISX DT Solution Promotes Digital Transformation of the Manufacturing Industry	曾祥宇, 上海湃睿信息科技有限公司, 副总经理 Xiangyu Zeng, Vice General Manager, Shanghai PISX
15:30 - 16:00	未来制造 数字之道 — 实现电子行业数字化正当时 The Way to Digitization in Future Manufacturing-It's Time That Digitization Be Achieved in the Electronic Industry	赵海涛, 西门子(中国)有限公司, 高级咨询顾问 Haitao Zhao, Senior Advisor, Siemens (China) Co., Ltd.

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第二届中国数字化制造高峰论坛 The 2nd China Digital Manufacturing Summit

时间: 2019年4月25日 10:00-16:00 (星期四)

Time: 10:00-16:00, April 25th, 2019 (Thursday)

地点: 上海世博展览馆2号馆, 智慧剧院

Location: Smart Theatre, Shanghai World Expo Exhibition & Convention Center

时间/Time	议题/Topic	主讲人/Speaker
09:20 - 09:50	签到 Sign-in	
09:50 - 10:00	主办方致辞 Speech by Organizer	
10:00 - 10:30	工业物联网从智能到智造 Industrial IoT and INTELLIGENT Manufacturing	徐玉涛, 微软 (中国) 有限公司, 全渠道事业部首席技术顾问 Tory Xu, Principal Technical Evangelist, OCP, Microsoft China
10:30 - 11:00	LOA信息化平台: 个性化定制的高效智能办公平台 LOA Platform: Personalized, Customized Efficient Intelligent Office Platform	杨琳, 紫光日东科技 (深圳) 有限公司, 销售总监 Lin Yang, Sales Director, Unisplendour Suneast Technology (Shenzhen) Co., Ltd.
11:00 - 11:30	突破IT和OT的界限 — WAGO工业物联网方案Pushing the Boundary of IT and OT - WAGO Industrial IoT Solution	徐峰博士, 万可电子 (天津) 有限公司, 首席技术顾问 Zheng Xu, Dr., Chief Technical Adviser, WAGO Electronic (Tianjin) Co., Ltd.
11:30 - 12:00	高速数据的基础-网络建设的物理层保障 The Foundation of High-Speed Data - The Physical Layer Guarantee of Network Construction	福禄克测试仪器 (上海) 有限公司 FLUKE Corporation
12:00 - 13:20	午间休息 Lunch Break	
13:20 - 13:30	抽奖环节 Lucky Draw	
13:30 - 13:55	5G助力工业互联智造未来 Future Industrial Internet & Intelligent Manufacturing based on 5G	王卫东, 行业规划首席架构师, 中兴通讯股份有限公司 Weidong Wang, Chief Architect of Industry Planning, ZTE Corporation
13:55 - 14:20	智能工厂初探 Initial Exploration On Smart Factory	付岗, 菲尼克斯 (南京) 智能制造技术工程有限公司, MES & IT Integration部门高级经理
14:20 - 14:45	柔性制造中的数字化产线设计 Digital Production Line Design in Flexible Manufacturing	宋华振, 贝加莱工业自动化 (中国) 有限公司, 市场部经理 Huazhen Song, Marketing Manager, B&R Industrial Automation (Shanghai) Co., Ltd.

Conference Program

研讨会会议程



14:45 - 15:10	工业电脑模块化极简设计 Modular Minimalist Design of Industrial Computers	鲁越平, 成都阿普奇科技股份有限公司, 产品总监 Yueping Lu, Product Director, Chengdu APQ Science and Technology Co., Ltd.
15:10 - 15:35	面向未来的数字化工业—魏德米勒自动化、数字化解决方案 Industrial Digitalisation for the Future - Introduction of Weidmüller Automation and Digitalization Solution	黄晶荣, 魏德米勒电联接(上海)有限公司, 工业自动化产品及解决方案事业部经理 Jinghong Huang, BU Manager, Division -Automation Products & Solutions Weidmüller Interface (Shanghai) Co., Ltd.
15:35 - 16:00	ePlan 软件数字化解决方案 EPLAN Software & Service (Shanghai) Co., Ltd.	易盼软件(上海)有限公司 EPLAN Software & Service (Shanghai) Co., Ltd.



质胜之道—5G时代下的消费电子质量标准论坛

All Quality Matters – Consumer Electronics Quality Standard Forum in 5G Era

时间: 2019年4月24日 13:30-17:00 (星期三)

Time: 13:30-17:00, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆B2层, 5号会议室

Location: Meeting Room 5, B2/F, Shanghai World Expo Exhibition & Convention Center

时间/Time	议题/Topic	主讲人/Speaker
13:30 - 14:15	智能家居产品软件风险评估 Software Risk Assessment of Smart Home Products	周伟, 德国莱茵TÜV大中华区, 电子电气服务高级经理 Wei Zhou, Senior Manager, Electrical, TÜV Rheinland Greater China
14:15 - 14:45	5G时代的个人信息安全 Personal Information Safety in 5G Era	周源, 德国莱茵TÜV大中华区, 信息通信技术高级项目工程师 Joyoe Zhou, Senior Project Engineer, Digital Transformation & Cybersecurity, TÜV Rheinland Greater China
14:45 - 15:00	茶歇 Tea Break	
15:00 - 15:45	健康照明产品的质量评价体系 Quality Evaluation System of Health Lighting Products	王旻愷, 德国莱茵TÜV大中华区, 电子电气产品服务专家 Jimmy Wang, Expert, Electrical, TÜV Rheinland Greater China
15:45 - 16:15	智能家电安全标准新趋势与互联网 New Trends of Safety Standards for Smart Household Appliances and Internet	易壮成, 德国莱茵TÜV大中华区, 电子电气产品服务部门经理 Zhuangcheng Yi, Department Manager, Electrical, TÜV Rheinland Greater China
16:15 - 17:00	智能手机产品蓝光危害与视觉健康 Blu-ray Hazards of Smartphones and Visual Health	刘喜强, 德国莱茵TÜV大中华区, 电子电气产品服务副总经理 Stanley Liu, Vice General manager, Electrical, TÜV Rheinland Greater China

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第十三届NEPCON与智慧工厂1.0—电子制造的未来 主题研讨会

The 13th Themed Symposium of NEPCON and Smart Factory 1.0 - Future of Electronics Manufacturing

时间: 2019年4月24日 13:30-15:30 (星期三)

Time: 13:30-15:30, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆, 2R40

Location: 2R40, Shanghai World Expo Exhibition & Convention Center

“数据与数据分析为电子制造企业创造价值” 主题会议

Thematic Conference on "Data and Data Analysis Creates Value for Electronic Manufacturing Enterprises"

时间/Time	议题/Topic	主讲人/Speaker
13:30 - 14:00	基于大数据AI的预测性分析与维护技术 Prognostics Analysis and Predictive Maintenance Based on Big Data and AI	刘建, 上海应势信息科技有限公司, 执行董事 Jian Liu, Executive Director, Shanghai INGSII Information Technology Co., Ltd.
14:00 - 14:30	利用数字化双胞胎技术实现透明化生产 Using Digital Twins Technology to Realize Transparent Production	龙小昂, 深圳华龙讯达信息技术股份有限公司, 总经理 Xiaoang Long, General Manager, Shenzhen Hualong Xunda Information Technology Co., Ltd.
14:30 - 15:00	5G时代的智慧工厂工业互联网体系构架 Internet Architecture of Smart Factory Industrial in 5G Era	刘艳强, 倍福中国公司, 高级技术顾问 Yanqiang Liu, Senior Technical Consultant, Beckhoff China
15:00 - 15:30	互动交流及礼品派发 Interactive Exchanges and Gift Distribution	

时间: 2019年4月25日 10:15-15:30 (星期四)

Time: 10:15-15:30, April 25th, 2019 (Thursday)

地点: 上海世博展览馆2号馆, 2R40

Location: 2R40, Shanghai World Expo Exhibition & Convention Center

“电子制造智慧工厂整体规划与实施案例” 主题会议

Thematic Conference on "Overall Planning and Implementation Case of Electronics Manufacturing Smart Factories"

时间/Time	议题/Topic	主讲人/Speaker
10:15 - 10:40	电子制造行业智慧工厂顶层设计与案例分析 Top-Level Design and Case Analysis of Smart Factories in Electronics Manufacturing Industry	王书强, 智慧工厂研究院院长 Shuqiang Wang, Executive President, Smart Factory Institute
10:40 - 11:05	多品种小批量柔性生产企业的数字化转型 Digital Transition to Flexible, Variety and Small Batch Manufacturing Enterprises	李玟桦, 上海果栗自动化科技有限公司, 市场总监 Wenhua Li, Marketing Director, Shanghai Golytec Automation Technology Co., Ltd.



第十三届NEPCON与智慧工厂1.0—电子制造的未来 主题研讨会

The 13th Themed Symposium of NEPCON and Smart Factory 1.0 - Future of Electronics Manufacturing

时间: 2019年4月24日 13:30-15:30 (星期三)

Time: 13:30-15:30, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆, 2R40

Location: 2R40, Shanghai World Expo Exhibition & Convention Center

“电子制造智慧工厂整体规划与实施案例”主题会议

Thematic Conference on "Overall Planning and Implementation Case of Electronics Manufacturing Smart Factories"

时间/Time	议题/Topic	主讲人/Speaker
11:05 - 11:45	精益MES的规划与选型 Planning and Selection of Lean MES	葛睿宁, 诗道芬 (上海) 商务咨询有限公司, 智能制造中心总经理 Ruining Ge, General Manager, Intelligent Manufacturing Center, Staufen. Shanghai
11:45 - 12:00	互动交流及礼品派发 Interactive Exchanges and Gift Distribution	
12:00 - 13:30	午间休息 Lunch Break	

“协作机器人在电子制造行业创新应用”主题会议

Thematic Conference on "Innovative Applications of Collaborative Robots in Electronics Manufacturing Industry"

时间/Time	议题/Topic	主讲人/Speaker
13:30 - 14:00	机器人触觉的实现—ATI多轴力矩传感器 Realization of Robot Haptic - ATI Multi-Axis Force / Torque Sensors	白伟, 美国ATI工业自动化有限公司, 亚洲区总经理 Wei Bai, General Manager, ATI Industrial Automation Asia
14:00 - 14:30	无智能不协作—制造业智能协作的泛在化 When COBOT Meet Intelligence	王健, 科技自动化联盟秘书长 Jian Wang, China Science & Technology Automation Alliance
14:30 - 15:00	协作机器人与智能制造 Collaborative Robots and Intelligent Manufacturing	田玮, 销售总监, 优傲机器人贸易 (上海) 有限公司 Wei Tian, Sales Director, Universal Robots China
15:00 - 15:30	互动交流及礼品派发 Interactive Exchanges and Gift Distribution	



“智能可穿戴产品中印刷电子与微组装技术”创新论坛

Innovation Forum on "Printed Electronics & Micro-Assembly Technology in Smart Wearable Products"

时间: 2019年4月24日 13:30-16:30 (星期三)

Time: 13:30-16:30, April 24th, 2019 (Wednesday)

地点: 上海世博展览馆B2层, 7号会议室

Location: Meeting Room No.7, Floor B2

时间/Time	议题/Topic	主讲人/Speaker
13:00 - 13:30	会议签到 Sign-in	
13:30 - 14:10	高密度组装工艺质量及可靠性管控的若干要点分析 Key Points of Quality and Reliability Control of High Density Assembly Process	陆玉凤, 深圳长城开发科技股份有限公司, 中央实验室经理 Yufeng Lu, Shenzhen Kaifa Technology Co., Ltd. Central Laboratory Manager
14:10 - 14:50	纸电池在柔性印刷电子行业中的应用 Application of Paper Battery in Flexible Printing Electronics Industry	王海平, 江苏恩福赛柔性电子有限公司, 高级市场部经理 Haiping Wang, Senior Marketing Manager, Enfucell Flexible Electronics Ltd
14:50 - 15:30	智能可穿戴产品小型化对焊接技术的要求 Welding Technology Requirements for Miniaturization of Smart Wearable Products	刘哲, 中兴通讯股份有限公司, 制造工程研究院工艺研究部总工程师 Zhe Liu, Chief Engineer of Technology Research Department, Manufacturing Engineering Research Institute, ZTE
15:30 - 16:10	电子工程3D打印技术 3D Printing Technology for Electronics Engineering	尹恩怀博士, 西安瑞特三维科技有限公司, 技术总工 Dr. Enhuai Yin, Chief Engineer, Xi'an Ruite 3D Technology Co., Ltd.
16:10 - 16:30	现场热点探讨: 专家答疑、观众互动探讨问题 On-Site Discussions: Q&A, Interaction between the Audience and Experts	互动主持: 刘哲, 中兴通讯股份有限公司, 制造工程研究院工艺研究部总工程师 Host for Interaction Activities: Zhe Liu, Chief Engineer of Technology Research Department, Manufacturing Engineering Research Institute, ZTE 特邀嘉宾: 陆玉凤、王海平、刘哲、尹恩怀 Special Guest: Yufeng Lu, Haiping Wang, Zhe Liu, Enhuai Yin
16:30	会议抽奖及会议结束 Lucky Draw and End of Conference	

日本电子午间研讨会

JEOL Lunch Seminar

时间: 2019年4月24日-25日 12:00-13:00 (星期三-星期四)

Time: 12:00-13:00, April 24th-25th, 2019 (Wednesday-Thursday)

地点: 上海世博展览馆B2层, 11号会议室

Location: Meeting Room No.11, Floor B2

时间/Time	议题/Topic	主讲人/Speaker
12:00 - 13:00	新型SEM及Cross section polisher™截面抛光仪制样方法介绍 Introduction of Modern SEMs and Sample Preparation Method by Cross Section Polisher™	陈德祥, 捷欧路亚洲有限公司, 销售总监 Tan Teck Siong, Sales Director, JEOL ASIA PTE.LTD.

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2019 (第二十四届) 上海国际SMT技术高级研讨会

2019 (The 24th) Shanghai Int'l SMT High - level Conference

时间: 2019年4月25日 09:50-16:20 (星期四)

Time: 09:50-16:20, April 25th, 2019 (Thursday)

地点: 上海世博展览馆B2层, 5号会议室

Location: Meeting Room 5, B2/F, Shanghai World Expo Exhibition & Convention Center

时间/Time	议题/Topic	主讲人/Speaker
09:50 - 10:20	采用七轴电脑焊锡机器人提升直插元件的焊接品质 Improving Welding Quality of Plating Through Holes By Using Seven - Axis Computer - Aided Soldering Robots	尹斌杰, 迈力 (北京) 机器人科技有限公司, 总经理 Binjie Yin, General Manager, Manly Robot
10:20 - 10:50	用真空避免空洞缺陷 Avoid Voids with Vacuum	Ralf Wagenfuehr, CTO, Rehms Thermal Systems Dongguan
10:50 - 11:20	汽车电子模块质量需求 Quality Requirements for Automotive Electronic Modules	Kevin Yuan, 通用汽车电子股份有限公司, 供应商管理总监 Kevin Yuan, Director of Supplier Management, General Motors Electronics Co., Ltd.
11:20 - 12:00	SMT焊接零缺陷的全面智慧监控 Comprehensive Intelligent Zero - Defect Monitoring of SMT Welding	张坤泉, ESAMBER中国服务中心, 技术服务总监 Kunquan Zhang, Director of Technical Services, ESAMBER China Service Center
12:00 - 13:30	午间休息 Lunch Break	
13:30 - 13:40	抽奖环节 Lucky Draw	
13:40 - 14:20	制造过程与电子产品可靠性 Manufacturing Process and Reliability of Electronic Products	李建江, 上海忠麟电子企业有限公司, QA资深经理 Jianjiang Li, Senior Manager of QA, Shanghai SVA DD&TT Electronic Enterprise Co., Ltd.
14:20 - 14:50	线路板短路故障定位的快速实现 Fast Location of Short Circuit Faults in Circuit Boards	李志勇, ESAMBER中国服务中心, 资深技术经理 Zhiyong Li, Senior Technical Manager, ESAMBER China Service Center
14:50 - 15:20	航空电子产品生产过程的信息化实现探索 Exploration of Informatization in the Production Process of Aviation Electronics	张立明, 中国航发控制系统研究所, 高级工艺师 Liming Zhang, Senior Technician, AECC Aero Engine Control System Institute
15:20 - 15:50	汽车电子辅料管控技术解析 Analysis of Automotive Electronic Accessories Management and Control Technology	汪洋, 电子五所 (中国赛宝实验室), 分析中心主任 Yang Wang, Director of Analytical Center, Fifth Electronic Research Institute of MIIT (CEPREI)
15:50 - 16:20	高可靠无铅焊接材料设计及组织性能研究 Study on Design and Structure Property of High Reliability Lead - free Welding Materials	张富文, 北京康普锡威科技有限公司, 研发部经理、正高级工程师 Fuwen Zhang, Manager of R & D Department and Senior Engineer, Beijing COMPO Solder Co., Ltd.



2019 AUTOMOTIVE WORLD CHINA新能源汽车三电系统开发与测试技术大会

2019 AUTOMOTIVE WORLD CHINA Conference on Development and Testing Technologies for NEV Electromobility System

时间: 2019年4月25日 10:00-16:30 (星期四)

Time: 10:00-16:30, April 25th, 2019 (Thursday)

地点: 上海世博展览馆B2层, 2号会议室

Location: Meeting Room 2, B2/F, Shanghai World Expo Exhibition & Convention Center

主持嘉宾: 谢先宇, 上海机动车检测认证技术研究中心, 汽车整车及零部件检测中心副总工

Guest Host: Xianyu Xie, Deputy Chief Engineer of Automobile and Parts Testing Center at Shanghai Motor Vehicle Inspection Certification & Tech Innovation Center

电池系统的开发与测试 Development and Testing of Battery Systems

时间/Time	议题/Topic	主讲人/Speaker
09:30 - 10:00	签到 Sign-in	
10:00 - 10:30	2019新能源汽车及关键部件开发与测试市场趋势 NEV and Key Components Development and Testing Market Trends for 2019 (大纲内容: 1、新能源汽车政策变化的回顾及展望。2、市场前景及OEM的应对举措。3、整车产品及三电系统的发展趋势及对测试市场的挑战。4、三电系统测试市场格局及未来的趋势研判) (Outline: 1. Reviews and prospects of NEV policy changes 2. Market prospects and OEMs' countermeasures 3. Development trends of automobiles and electromobility systems and challenges towards the testing market 4. Electromobility system testing market structure analysis and prospect)	韩家骅, NE研究院, 高级分析师 Jiahua Han, Senior Analyst, NE Research Institute
10:30 - 11:00	新能源汽车动力电池系统测试与评价体系 Testing and Evaluation System of NEV Power Battery Systems (大纲内容: 1、国内外动力电池测试标准。2、动力电池测试评价。3、典型试验案例分析) (Outline: 1. Introduction of testing standards for traction battery at home and abroad 2. Test and evaluation of traction battery 3. Typical test cases analysis)	谢先宇, 上海机动车检测认证技术研究中心, 汽车整车及零部件检测中心副总工 Xianyu Xie, Deputy Chief Engineer of Automobile and Parts Testing Center, Shanghai Motor Vehicle Inspection Certification & Tech Innovation Center
11:00 - 11:30	BYD新能源电池开发及测试技术新进展 New Progress in NEV Battery Development and Testing Technology of BYD (大纲内容: 1、测试体系升级的需求。2、比亚迪内部短路研究。3、系统思维指导下的评价体系) (Outline: 1. Requirements for upgrading testing systems 2. BYD's research in internal short circuit 3. Evaluation system under the guidance of systematic thinking)	王高武, 比亚迪, 第二事业部SZD测试验证部经理 Gaowu Wang, Manager of SZD Testing and Verification Department, Second Division, BYD

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Conference Program

研讨会议程



11:30 - 12:00 高压电池系统设计与测试
Design and Testing of High Voltage Battery Systems
(大纲内容: 1、高压电池系统需求与设计。2、系统设计与试验设计)
(Outline: 1. Requirements and Design of High Voltage Battery Systems
2. System Design and Test Design)

吴海平, PSA电池项目经理
Haiping Wu, Battery Project Manager, PSA

12:00 - 13:30 午餐 Lunch

主持嘉宾: 曾丽平, NE时代创始人、NE研究院院长
Guest Host: Liping Zeng, Founder, NE Times and President, NE Research Institute

电池系统的开发与测试 Development and Testing of Battery Systems

时间/Time	议题/Topic	主讲人/Speaker
13:30 - 14:00	动力电池发展趋势分析 Analysis of Power Battery Development Trends (大纲内容: 1.细谈三元和LFP的趋势。2、模组标准化趋势。3、快充和高倍率的趋势。4、固态电池的趋势) (Outline: 1. Trends in NCM and LFP 2. Trends in standard module design 3. Trends in fast charging and high charging rate batteries 4. Trends in solid state batteries)	杨建军, 爱驰汽车电池, 高级经理 Jianjun Yang, Senior Manager, Aiyas Auto Battery
14:00 - 14:30	高性能模拟技术在锂电池管理系统中的应用 Application of High Performance Analog Technology in Lithium Battery Management Systems (大纲内容: 1、BMS的实时监测性能。2、通过模拟技术构建安全设计的核心。3、低成本保证通信可靠性) (Outline: 1. Performance of Measurement values BMS monitor 2. Core design of safety providing by analog technology 3. Robustness of communication with cost saving)	王成, 亚德诺半导体 (ADI), 电池管理系统资深应用工程师 Cheng Wang, Senior Application Engineer of Battery Management Systems, Analog Devices, Inc. (ADI)
14:30 - 15:00	动力电池管理系统中功能安全设计的重要性 Importance of Functional Safety Design in Power Battery Management Systems (大纲内容: 新能源汽车中电池管理系统中引入功能安全对于提高电池系统的安全及整车的相关介绍) (Outline: Introduction of how functional safety in NEV battery management systems improves the safety of battery systems and vehicles.)	刘洋, 东莞钜威动力, 副总经理 Yang Liu, Vice General Manager, Dongguan PowerWise Technology
15:00 - 15:30	茶歇 Tea break	

15:30 - 16:00

新能源动力电池系统测试技术分析与研究—电气安全专题

Testing Technology Analysis and Research of REESS - Electrical Safety
(大纲内容: 1.电气安全方案。2、具体的电气安全条目。3、深入讲解等电位要求。4、碰撞后电气安全要求。5、成功案例)

(Outline: 1. Electrical Safety Solution 2. Electrical safety requirements
3. How to equipotential bonding? 4. Post crash electrical Safety 5.
Successful Cases Show)

彭波, TÜV莱茵大中华区, 交通服务专家

Bo Peng, Traffic Service Specialist, TÜV Rheinland Greater China

16:00 - 16:30

动力电池测试设计和数据分析

Testing Design and Data Analysis of EV Cells

(大纲内容: 1、传统动力电池测试方法介绍。2、适用于新能源汽车应用的新型测试方法探索
3、测试数据的分析: 价值挖掘)

(Outline: 1. Introduction to traditional EV cell testing methods 2.
Exploration of new testing methods for NEV applications 3. Analysis of
testing data: value mining)

蒋治亿, 中科大博士、重庆朱雀新能源科技有限公司, 总经理

Zhiyi Jiang, Ph.D. of University of Science and Technology of China, and
General Manager of Chongqing Royalsoft New Energy Science and Technology
Co., Ltd.



2019 AUTOMOTIVE WORLD CHINA新能源汽车三电系统开发与测试技术大会

2019 AUTOMOTIVE WORLD CHINA Conference on Development and Testing Technologies for NEV Electromobility System

时间: 2019年4月26日 10:00-16:30 (星期五)

Time: 10:00-16:30, April 26th, 2019 (Friday)

地点: 上海世博展览馆B2层, 2号会议室

Location: Meeting Room 2, B2/F, Shanghai World Expo Exhibition & Convention Center

主持嘉宾: 曹红飞, 龙芯电驱动、原华域电动总工程师

Guest Host: Hongfei Cao, Chief Engineer, Loongson Electric Drive and Former Chief Engineer of Huayu Electric Systems

驱动系统的开发与测试 Development and Testing of Drive Systems

时间/Time	议题/Topic	主讲人/Speaker
09:30 - 10:00	签到 Sign-in	
10:00 - 10:30	新能源驱动系统技术进展及测试要求 Technical Progress and Testing Requirements of NEV Drive Systems (大纲内容: 1、新能源驱动系统发展方向及测试要求。2、新能源驱动系统技术进展。3、新能源驱动系统应用趋势预测) (Outline: 1. Development directions and testing requirements of NEV drive systems 2. Technological progress in NEV drive systems 3. Forecasts of NEV drive system application trends)	张鑫, NE研究院, 高级分析师 Xin Zhang, Senior Analyst, NE Research Institute
10:30 - 11:00	驱动电机系统测试技术分析与研究 Analysis and Research of Driving Motor System Testing Technology (大纲内容: 驱动电机检测标准体系介绍、测试项目介绍、驱动电机测试技术与研究) (Outline: Introduction to the driving motor testing standards system, test items, testing technology and research)	吴诗宇, 重庆车辆检测研究院有限公司, 动力部电气室主任 Shiyu Wu, Director of Electrical Department, Power Division, Chongqing Vehicle Test & Research Institute
11:00 - 11:30	新能源汽车车用扁铜线电机技术 Hair-pin Motor Technology for NEVs (大纲内容: 1、扁线电驱的技术特点。2、扁线电机的关键技术问题。3、扁线电枢典型样机的技术解读) (Outline: 1. Technical characteristics of Hair-pin drives motor 2. Key technical issues about Hair-pin motors 3. Technical interpretation of typical Hair-pin typical prototypes)	曹红飞, 龙芯电驱动, 总工程师 Hongfei Cao, Chief Engineer, Loongson Electric Drive



Conference Program

研讨会议程

11:30 - 12:00	电驱动系统试验评价技术 Test and Evaluation Technology of Electrical Driving System (大纲内容: 1、电驱动系统试验方法。2、电驱动系统试验评价指标。3、电驱动系统试验技术开发) (Outline: 1. Test methods of electric drive systems 2. Test evaluation indicators of electric drive systems 3. Development of test technology of electric drive systems)	王斯博, 中国第一汽车集团有限公司, 电驱试验开发领域经理 Sibo Wang, Manager of Electric Drive Test and Development, China FAW Group Corporation
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12:00 - 13:30 午餐 Lunch

主持嘉宾: 曾丽平, NE时代创始人、NE研究院院长
 Guest Host: Liping Zeng, Founder, NE Times and President, NE Research Institute

驱动系统的开发与测试

Development and Testing of Drive Systems

时间/Time	议题/Topic	主讲人/Speaker
13:30 - 14:00	如何基于运行工况计算驱动器功率模块的寿命 How to calculate the lifetime consumption of power module based on mission profile (大纲内容: 仿真计算方法概述、逆变器仿真模型、热模型: 简化福斯特模型表征、雨流算法、韦伯统计分布) (Outline: Simulation Methodology Overview, Inverter simulation model, Thermal Model: simplified Foster Model representation, ASTM Rainflow Algorithm ASTM, Weibull statistics)	曲树笋, 英飞凌科技(中国)有限公司, 资深主任工程师 Shusun Qu, Senior Director Engineer, Infineon Technologies (China) Co., Ltd.
14:00 - 14:30	电驱动功率模块的发展与测试 Development and Testing of Electric Drive Power Modules (大纲内容: 1、电驱系统对功率模块的主要要求。2、电驱功率模块的技术发展趋势。3、电驱功率模块的测试) (Outline: 1. Main requirements for power modules in electric drive systems 2. Technical development trends of electric drive power modules 3. Testing of electric drive power modules)	吴海平, 比亚迪第六事业部, IGBT芯片产品部高级研发经理 Haiping Wu, Senior R&D Manager of IGBT Chip Product Department, Sixth Division, BYD
14:30 - 15:00	动力总成电气化及48V系统解决方案 Electrification of Powertrain and 48V System Solutions (大纲内容: 动力总成的转型、电气化市场分析、48V系统创新解决方案) (Outline: Transformation of Powertrain, electrification Powertrain market analysis, innovative 48V system solutions)	夏伟, 索恩格汽车部件(中国)有限公司, 市场总监 Wei Xia, Marketing Director, SEG Automotive Products (China) Co., Ltd.
15:00 - 15:30	茶歇 Tea Break	
15:30 - 16:00	变频电量的测试与计量-新能源汽车 Test and Measurement of variable frequency power-NEV (大纲内容: 1、正确的测量方法 2、准确的测量仪器 3、科学的计量手段) (Outline: 1. Correct measurement method; 2. Correct measurement devices; 3. Scientific measurement)	徐伟专, 国家变频电量测量仪器计量站工程技术中心首席专家、湖南银河电气有限公司董事长 Weizhuan Xu, Chief Expert, National Variable Frequency Electricity Metrology Station, President of Hunan Yinhe Electric Co., Ltd

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Conference Program

研讨会议程



16:00 - 16:30

新能源汽车动力总成系统（混动、增程和纯电动）的前瞻技术和协同创新开发

Prospective Technology and Collaborative Innovation Development of NEV Powertrain Systems (HEV, REEV and EV)

(大纲内容: 1、当前主流拓扑结构的混动和增程系统在产品架构、系统成本和总体性能的细节性比较。2、不同整车产品需求定义下的各类混动和增程系统化解决方案。3、纯电动动力总成三合一系统的创新方向、设计要点、工程案例分享。4、混动和纯电动系统的技术创新、产品方案、样件样车和工程化开发案例和总结)

(Outline: 1. Detailed comparison of product architecture, system cost and overall performance between HEV and REEV powertrain system based on current mainstream topology structure 2. Various HEV and REEV powertrain system solutions under different definitions of vehicle product requirements 3. Innovation directions, key design points, and project cases of three-in-one electric powertrain systems 4. Technical innovation, product plans, prototype parts and cars, engineering project development cases and summary of HEV and BEV systems).

陈利君, 上海易矩汽车技术有限公司, 总经理

Lijun Chen, General Manager, Shanghai EcoTorc Vehicle Technology

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“中国电子工业静电防护2019”专业论坛

2019 Forum on Electrostatic Protection in China's Electronics Manufacturing Industry

时间: 2019年4月25日 13:30-16:30 (星期四)

Time: 13:30-16:30, April 25th, 2019 (Thursday)

地点: 上海世博展览馆B2层, 7号会议室

Location: Meeting Room No.7, Floor B2

时间/Time	议题/Topic	主讲人/Speaker
13:30 - 14:15	电子工业工作人员静电防护要点解析—人体静电防护知多少 Essential Points of Electrostatic Protection for Electronics Industry Workers - Things You Need to Know About Electrostatic Protection	徐明, 上海防静电工业协会, 常务副秘书长 Ming Xu, Deputy Secretary-General, Shanghai Electrostatic Protective Industrial Association
14:15 - 15:00	新型非湿度依赖永久型防静电产品的应用和发展 Application and Development of New Non - Humidity Dependent Permanent Antistatic Products	肖培玉, 上海君江科技有限公司, 经理 Peiyu Xiao, Manager, Shanghai Junjiang Technology Co., Ltd.
15:00 - 15:45	SMT过程的静电防护及智能管理 Electrostatic Protection and Intelligent Management of SMT Processes	张明, 上海防静电工业协会, 专家委员会主任 Ming Zhang, Director of the Expert Committee, Shanghai Electrostatic Protective Industrial Association
15:45 - 16:30	低钳位电压的ESD保护应用 Application of ESD Protection with Low Clamp Voltage	胡光亮, 上海雷卯电子科技有限公司, 技术总监 Guangliang Hu, Technical Director, Shanghai Leiditech Electronic Technology Co., Ltd.

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NEPCON工程师沙龙暨SMT之家会员见面会

NEPCON Engineers' Salon and SMT Home Member Gathering

时间: 2019年4月26日 13:00-15:45 (星期五)

Time: 13:00-15:45, April 26th, 2019 (Friday)

地点: 上海世博展览馆, 智慧剧院

Location: Smart Theatre, Shanghai World Expo Exhibition & Convention Center

时间/Time	议题/Topic
13:00 - 13:45	按报名名单签到并领取文化衫, 会员、版主在活动现场交流、自由合影, 或者参观展会 (签到场地: 智慧剧院) Sign - in and T - shirt Collection, On - Site Communication and Photographing (at Smart Theatre)
13:45 - 14:05	见面会开始, 致辞; 版主、会员自我介绍 Opening Address of the Meet - and-Greet; Self - Introduction of The Moderator and Members
14:05 - 14:30	网络时代的SMT工程师如何自我增值 (9) How SMT Engineers Boost Their Self-Value in the Internet Age (9)
14:30 - 15:35	Q&A有奖问答, 管理团队现场解答会员疑问 Give - Away Q & A
15:35 - 15:45	与会人员集体合影留念, 结束 Group-Photographing upon Conclusion

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03

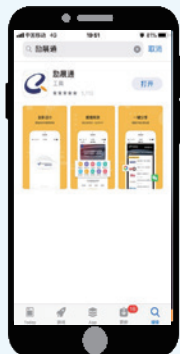
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04

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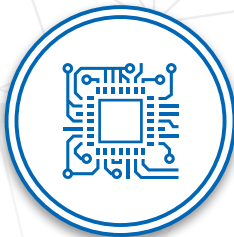
NEPCON ASIA 2019

六展合一，打造亚洲电子制造产业连通平台

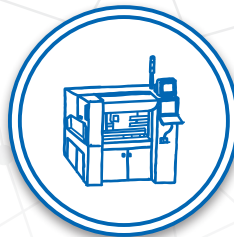
6 Exhibitions Unity-Platform Connects Asian Electronics Manufacturing Industry Together

2019.8.28-30 | 深圳会展中心 | Shenzhen Convention & Exhibition Center

同期展会：
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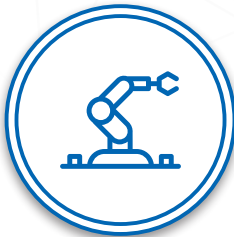
印制电路板
Printed Circuit Board



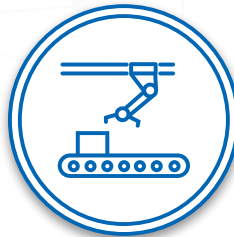
表面贴装技术
Surface Mount Technology



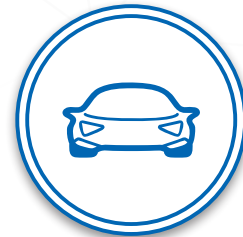
自动化测试技术
Test & Measurement Technology



自动化组装技术
Automatic Assembly Technology



智慧工厂
Smart Factory



汽车电子
Automotive Electronics

60,000m²+

展示面积
sqm

60,000+

专业买家
Professional buyers

800+

参展品牌
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以上数字为预计数字 | Figures above are estimated.